



**Pin Description<sup>(1)</sup>**

Pin #	Name	Type	Description
1, 2	Q1+, Q1-	Output	Differential output pair, LVPECL/ CML interface level.
3	V <sub>DD</sub>	Power	Power Supply
4, 5	Q2+, Q2-	Output	Differential output pair, LVPECL/ CML interface level.
6	V <sub>DD</sub>	Power	Power Supply
7, 8	Q3+, Q3-	Output	Differential output pair, LVPECL/ CML interface level.
9	V <sub>DD</sub>	Power	Power Supply
10, 11	Q4+, Q4-	Output	Differential output pair, LVPECL/ CML interface level.
12	EN	Input	Synchronous Output Enable, with internal 25k-ohm pull-up resistor. Logic high selects enable, and logic low selects disable.
13	TS	Input	Type Select. Input type select between high and low bias voltage at V <sub>TH</sub> , with internal 25k-ohm pull-up resistor. Logic high selects high bias voltage, and logic low selects low bias voltage
14	REF_IN0-	Input	Differential IN negative input, AC and DC coupled
15	VREF-AC	Output	Reference Voltage: Biased to V <sub>DD</sub> -1.4V. Used when AC coupling inputs
16	V <sub>TH</sub>	Output	Differential pair IN0 center-tap node
17	REF_IN0+	Input	Differential IN positive input, AC and DC coupled
18	IS	Input	Input Select. Select between IN0 and IN1, with internal 25k-ohm pull-up resistor. Logic high selects IN1, and logic low selects IN0.
19	REF_IN1-	Input	Differential IN1 negative input, AC coupled only
20	REF_IN1+	Input	Differential IN1 positive input, AC coupled only
21	OS	Input	Output Select. Output type select between LVPECL/ CML, with internal 25k-ohm pull-up resistor. Logic high selects LVPECL, and logic low selects CML.
22	V <sub>DD</sub>	Power	Power Supply
23, 24	Q0+, Q0-	Output	Differential output pair, LVPECL/ CML interface level.

**Functional Description**

REF_IN+	REF_IN-	EN	Q+	Q-
0	1	1	0	1
1	0	1	1	0
X	X	0	0	1

**Select Pin Descriptions**

OS	Q+	Q-
0	CML	CML
1	LVPECL	LVPECL
NC	LVPECL	LVPECL

**Maximum Ratings** (Over operating free-air temperature range)

Storage Temperature.....	-65°C to +155°C
Ambient Temperature with Power Applied.....	-40°C to +85°C
3.3V Core Supply Voltage .....	-0.5 to +4.6V
ESD Protection (HBM) .....	2000V

**Note:**

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**DC Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V <sub>DD</sub>	Core Power Supply Voltage		3.0		3.6	V
			2.375		2.625	V
T <sub>A</sub>	Ambient Temperature		-40		85	°C
I <sub>DD</sub>	Power Supply Current	No load, max V <sub>DD</sub>			170	mA
R <sub>DIFF_IN</sub>	Differential Input Resistance (REF_IN+ to REF_IN-)		90	100	110	Ω
V <sub>IH</sub>	Input High Voltage		1.2		V <sub>DD</sub> - 0.9	V
V <sub>IL</sub>	Input Low Voltage		0.4		V <sub>IH</sub> - 0.1	V
V <sub>IN</sub>	Input Voltage Swing		0.1		1.7	V
V <sub>DIFF_IN</sub>	Differential Input Swing		0.2			V
V <sub>REF-AC</sub>	Output Reference Voltage		V <sub>DD</sub> -1.50	V <sub>DD</sub> -1.30	V <sub>DD</sub> -1.15	V

**LVCMOS/LVTTL DC Characteristics** (T<sub>A</sub> = -40°C to +85°C, V<sub>DD</sub> = 2.5V ±5% to 3.3V ±10%)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V <sub>IH</sub>	Input High Voltage		2.0		V <sub>DD</sub>	V
V <sub>IL</sub>	Input Low Voltage		0		0.8	
I <sub>IH</sub>	Input High Current		-125		20	μA
I <sub>IL</sub>	Input Low Current		-300			μA

**LVPECL DC Characteristics** ( $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{DD} = 3.3\text{V} \pm 10\%$ ,  $2.5\text{V} \pm 5\%$ )

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$V_{OH}$	Output High Voltage	$V_{DD} = 3.3\text{V} \pm 10\%$	$V_{DD}-1.4$	$V_{DD}-1.145$	$V_{DD}-0.76$	V
		$V_{DD} = 2.5\text{V} \pm 5\%$	$V_{DD}-1.1$	$V_{DD}-0.95$	$V_{DD}-0.8$	V
$V_{OL}$	Output Low Voltage	$V_{DD} = 3.3\text{V} \pm 10\%$	$V_{DD}-2.1$	$V_{DD}-1.945$	$V_{DD}-1.6$	V
		$V_{DD} = 2.5\text{V} \pm 5\%$	$V_{DD}-1.75$	$V_{DD}-1.6$	$V_{DD}-1.4$	V
$V_{OUT}$	Output Voltage Swing	Single Ended, $V_{DD} = 3.3\text{V}$	550	800		mV
		Single Ended, $V_{DD} = 2.5\text{V}$				
$V_{DIFF\_OUT}$	Differential Output Voltage Swing	$V_{DD} = 3.3\text{V}$ , $f \leq 5\text{ GHz}$	1100	1600		mV
		$V_{DD} = 2.5\text{V}$ , $f \leq 3\text{ GHz}$				

**CML DC Characteristics** ( $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{DD} = 3.3\text{V} \pm 10\%$ ,  $2.5\text{V} \pm 5\%$ )

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$V_{OUT}$	Output Voltage Swing	Single Ended	325	400		mV
$V_{DIFF\_OUT}$	Output Differential Voltage Swing	$f \leq 3\text{GHz}$	650	800		mV

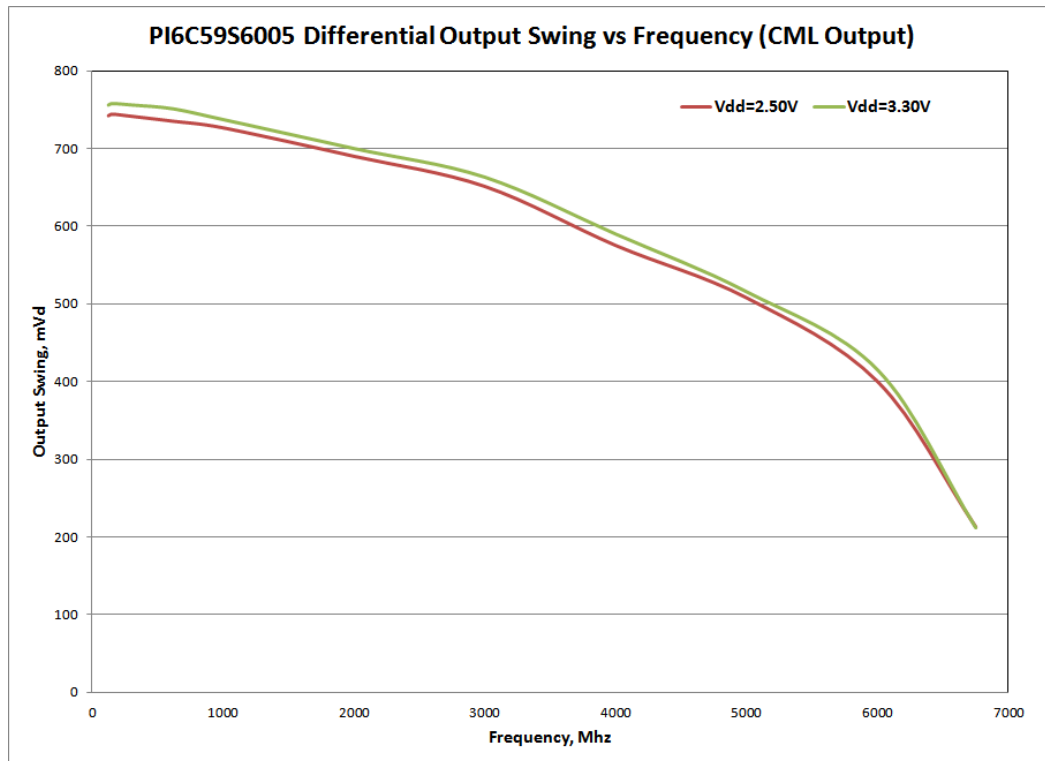
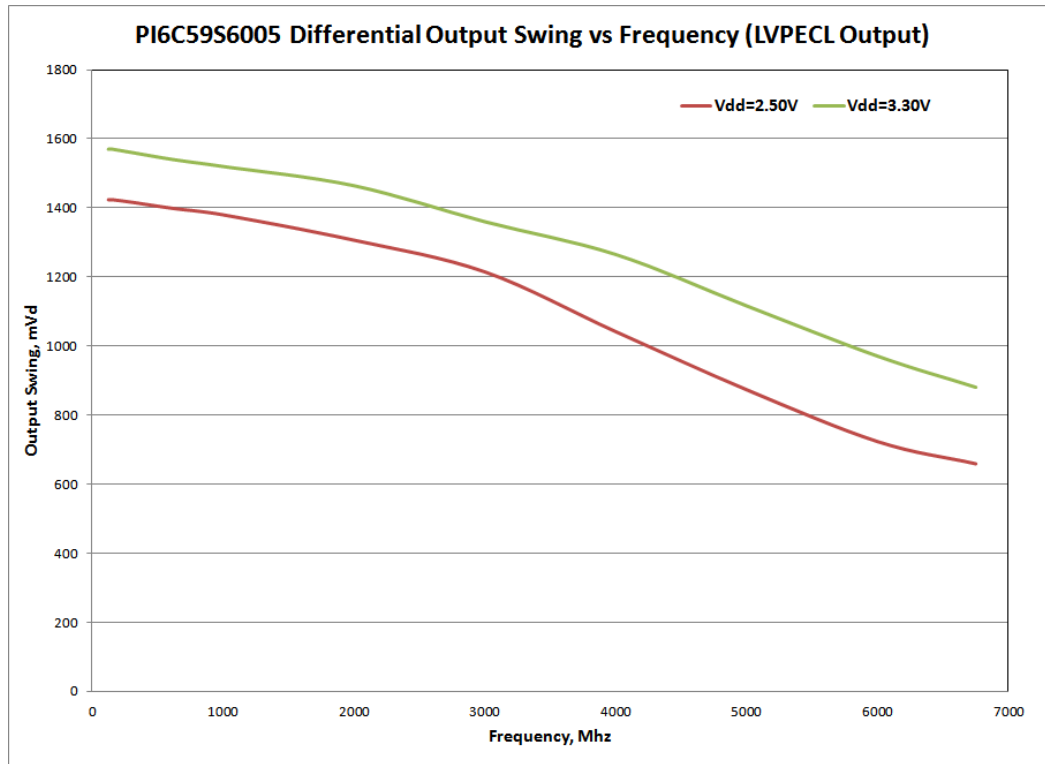
**AC Characteristics** ( $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{DD} = 3.3\text{V} \pm 10\%$ ,  $2.5\text{V} \pm 5\%$ )

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$f_{max}$	Output Frequency			6		GHz
$t_{pd}$	Propagation Delay <sup>(1)</sup>				400	ps
$T_{sk}$	Output-to-output Skew <sup>(2)</sup>				20	ps
	Device to Device skew				200	ps
$T_s$	Setup time			240		ps
$T_h$	Hold time			240		ps
$t_r/t_f$	Output Rise/Fall time	20% - 80%	40		90	ps
$t_{odc}$	Output duty cycle	$f \leq 1\text{ GHz}$	48		52	%
		$1\text{ GHz} \leq f < 6\text{ GHz}$	40		60	%
$t_j$	Buffer additive jitter RMS	156.25MHz with 12KHz to 20MHz integration range (LVPECL)		10		fs
		156.25MHz with 12KHz to 20MHz integration range (CML)		40		fs

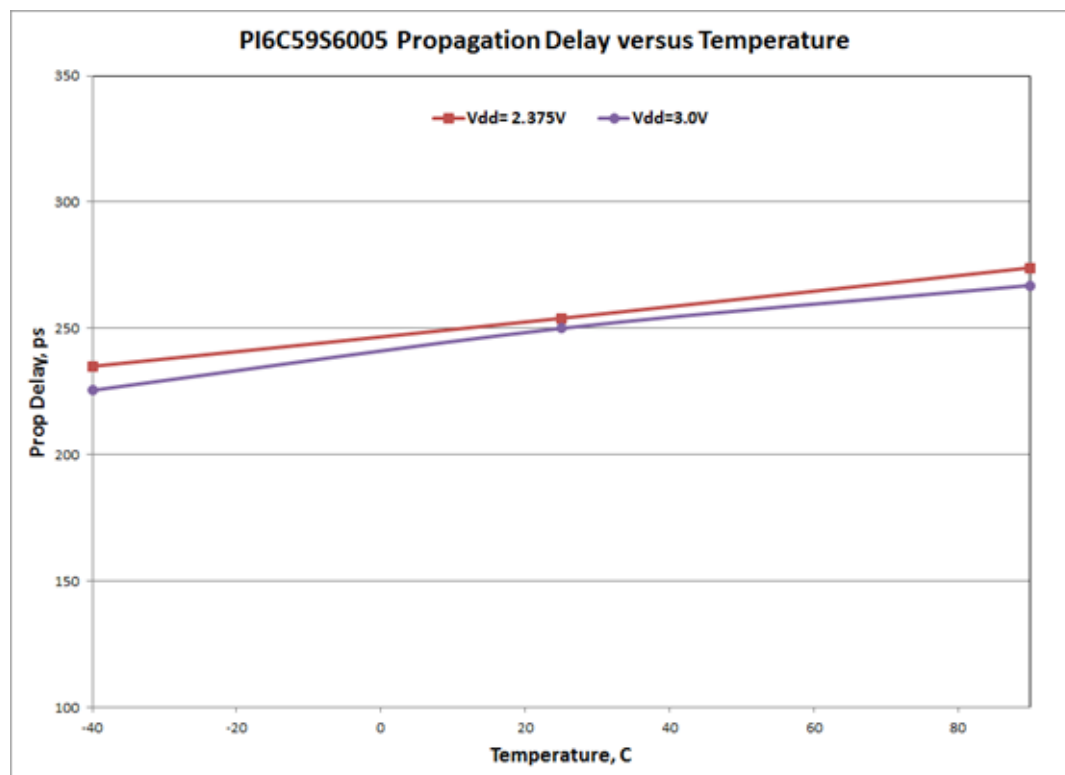
**Notes:**

1. Measured from the differential input to the differential output crossing point
2. Defined as skew between outputs at the same supply voltage and with equal loads. Measured at the output differential crossing point

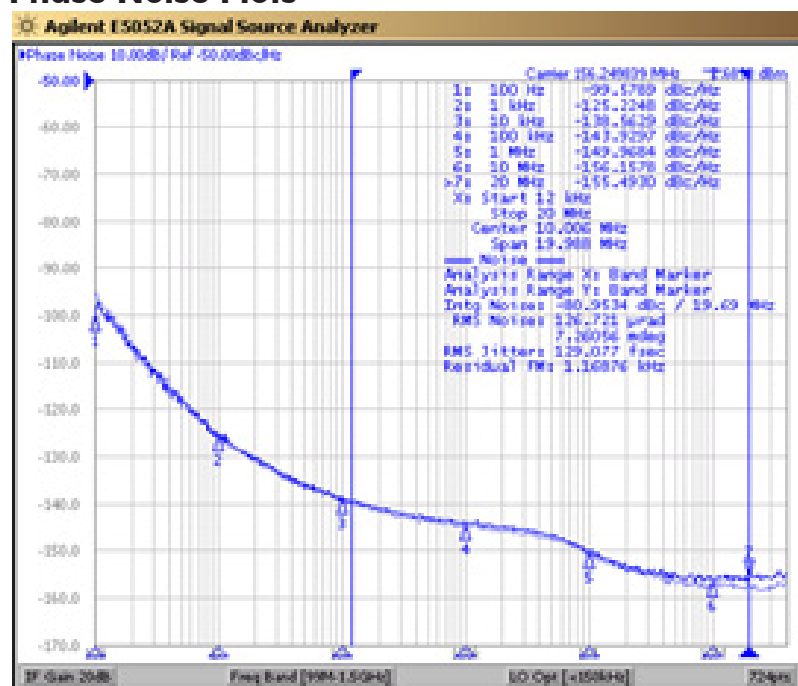
## Output Swing vs Frequency



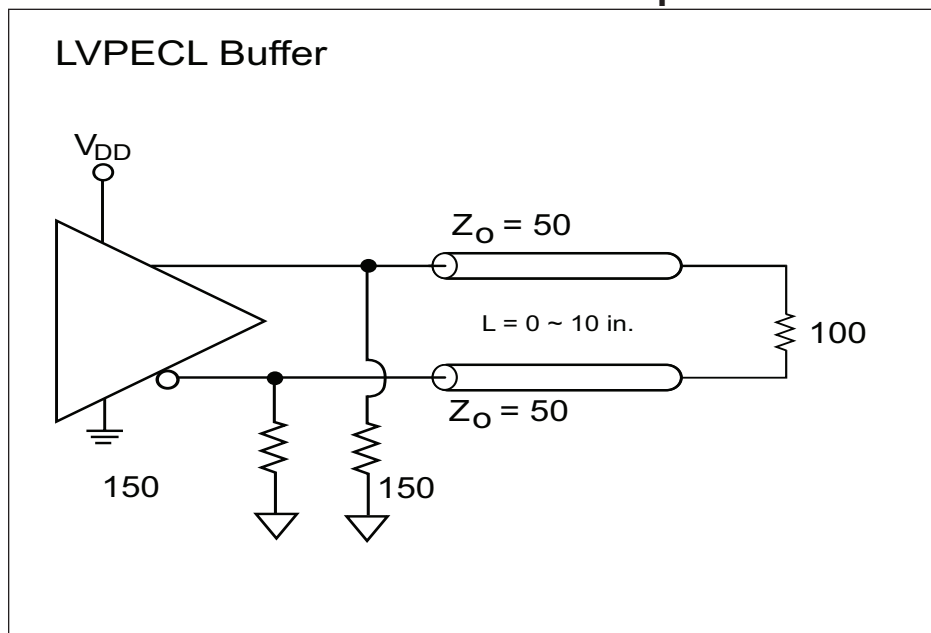
## Average Propagation Delay vs Temperature



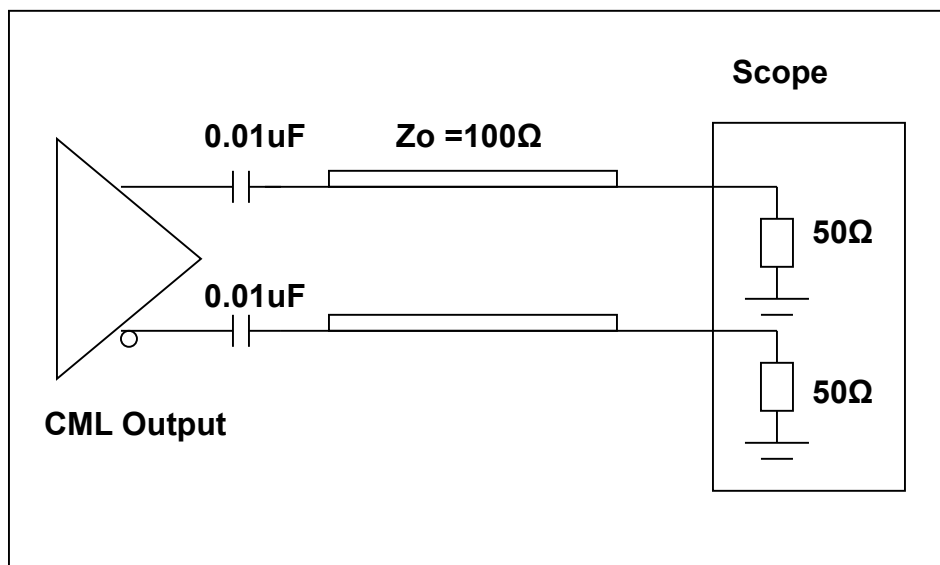
## Phase Noise Plots



### Configuration Test Load Board Termination for LVPECL Outputs



### Configuration Test Load Board Termination for CML Outputs



### Thermal Information

Symbol	Description	Condition	
$\Theta_{JA}$	Junction-to-ambient thermal resistance	Still air	54.4 °C/W
$\Theta_{JC}$	Junction-to-case thermal resistance		40.8 °C/W

## Application information

### Suggest for Unused Inputs and Outputs

#### LVC MOS Input Control Pins

It is suggested to add pull-up=4.7k and pull-down=1k for LVC-MOS pins even though they have internal pull-up/down but with much higher value ( $\geq 50k$ ) for higher design reliability.

#### REF\_IN= / REF\_IN- Input Pins

They can be left floating if unused. For added reliability, connect  $1k\Omega$  to GND.

#### Outputs

All unused outputs are suggested to be left open and not connected to any trace. This can lower the IC power supply power.

### Power Decoupling & Routing

#### VDD Pin Decoupling

As general design rule, each VDD pin must have a 0.1uF decoupling capacitor. For better decoupling, 1uF can be used. Locating the decoupling capacitor on the component side has better decoupling filter result as shown in Fig. 1.

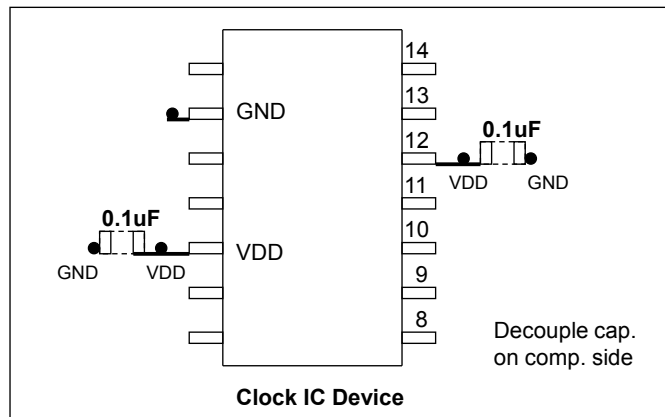


Fig 1: Placement of Decoupling caps

#### Differential Clock Trace Routing

Always route differential signals symmetrically, make sure there is enough keep-out space to the adjacent trace ( $>20mil.$ ). In 156.25MHz XO drives IC example, it is better routing differential trace on component side as the following Fig. 2.

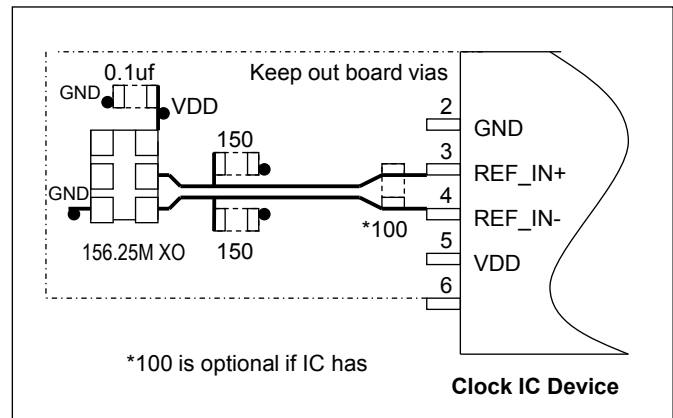


Fig 2: IC routing for XO drive

Clock timing is the most important component in PCB design, so its trace routing must be planned and routed as a first priority in manual routing. Some good practices are to use minimum vias (total trace vias count  $<4$ ), use independent layers with good reference plane and keep other signal traces away from clock traces ( $>20mil.$ ) etc.



## LVPECL and LVDS Input Interface

### LVPECL and LVDS DC Input

LVPECL and LVDS clock input to this IC is connected as shown in the Fig. 3.

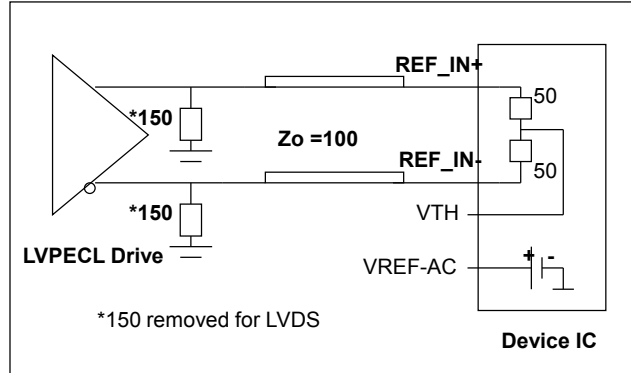


Fig 3: LVPECL/ LVDS Input

### LVPECL and LVDS AC Input

LVPECL and LVDS AC drive to this clock IC requires the use of the VREF-AC output to recover the DC bias for the IC input as shown in Fig. 4

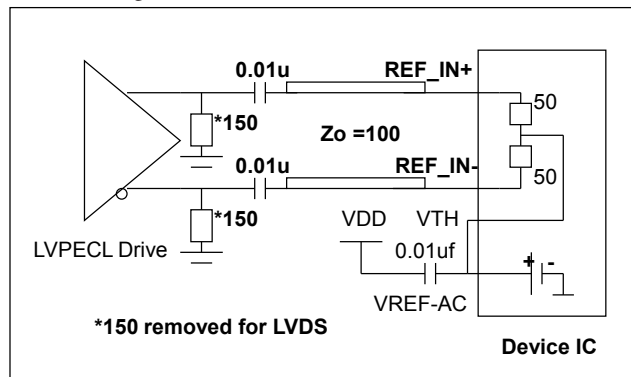


Fig 4: LVPECL/ LVDS AC Coupled Input

### CML AC-Coupled Input

CML AC-coupled drive requires a connection to VREF-AC as shown in Fig. 5. The CML DC drive is not recommended as different vendors have different CML DC voltage level. CML is mostly used in AC coupled drive configuration for data and clock signals.

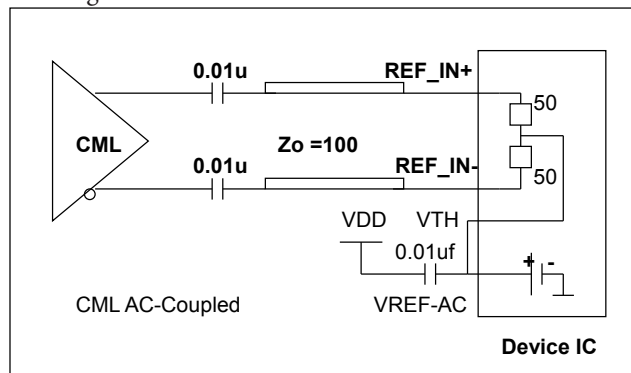


Fig 5: CML AC-Coupled Input Interface

### HCSL AC-Coupled Input

It is suggested to use AC coupling to buffer PCIe HCSL 100MHz clock since its  $V_{cm}$  is relatively low at about 0.4V, as shown in Fig. 6.

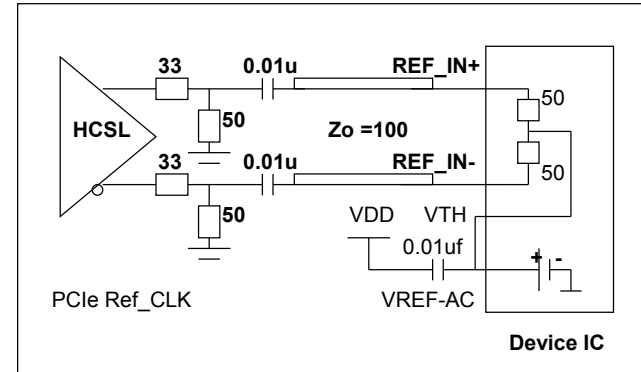


Fig 6: HCSL AC-Coupled Input Interface

### CMOS Clock DC Drive Input

LVC MOS clock has voltage  $V_{oh}$  levels such as 3.3V, 2.5V, 1.8V. CMOS drive requires a  $V_{cm}$  design at the input:  $V_{cm} = \frac{1}{2}$  (CMOS V) as shown in Fig. 7.  $R_s = 22 \sim 33\Omega$  typically.

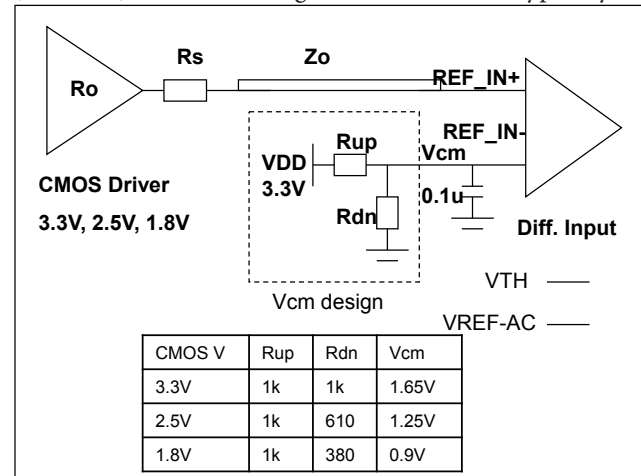


Fig 7: CMOS DC Input Vcm Design

## Device LVPECL Output Terminations

### LVPECL Output Popular Termination

The most popular LVPECL termination is 150ohm pull-down bias and 100ohm across at RX side. Please consult ASIC data-sheet if it already has 100ohm or equivalent internal termination. If so, do not connect external 100ohm across as shown in Fig. 8. This popular termination's advantage is that it does not allow any bias through from  $V_{DD}$ . This prevents  $V_{DD}$  system noise coupling onto clock trace.

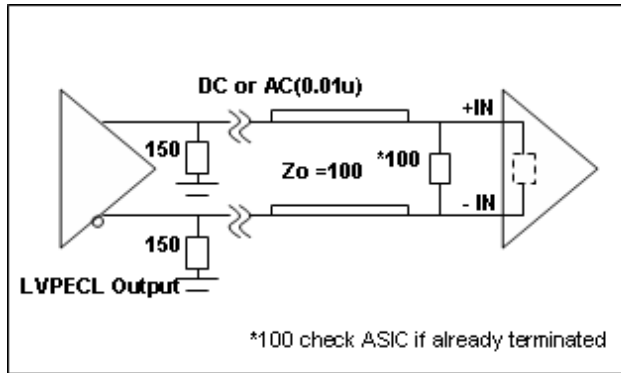


Fig. 8 LVPECL Output Popular Termination

### LVPECL Output Thevenin Termination

Fig. 9 shows LVPECL output Thevenin termination which is used for shorter trace drive (<5in.), but it takes  $V_{DD}$  bias current and  $V_{DD}$  noise can get onto clock trace. It also requires more component count. So it is seldom used today.

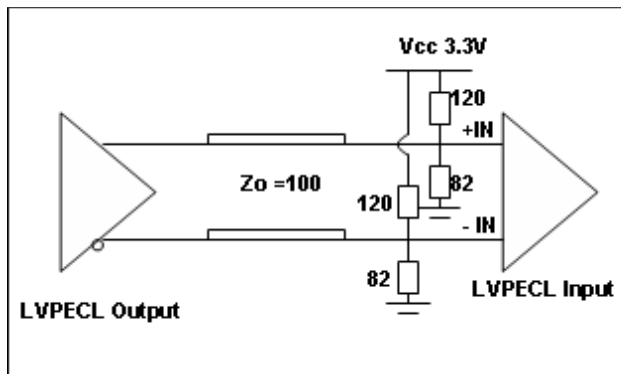


Fig. 9 LVPECL Thevenin Output Termination

### LVPECL Output AC Thevenin Termination

LVPECL AC Thevenin terminations require a 150ohm pull-down before the AC coupling capacitor at the source as shown in Fig. 10. Note that pull-up/down resistor value is swapped compared to Fig. 9. This circuit is good for short trace (<5in.) application only.

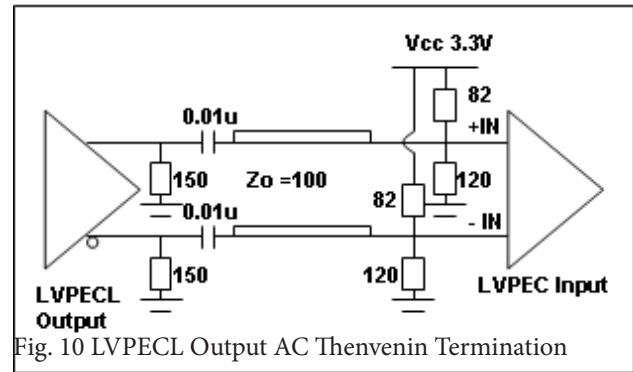


Fig. 10 LVPECL Output AC Thenvenin Termination

### LVPECL Output Drive HCSL Input

Using the LVPECL output to drive a HCSL input can be done using a typical LVPECL AC Thenvenin termination scheme. Use pull-up/down 450/60ohm to generate  $V_{cm}=0.4V$  for the HCSL input clock. This termination is equivalent to 50Ohm load as shown in Fig. 11.

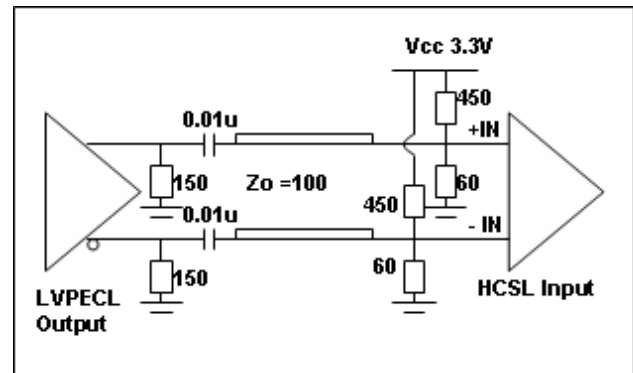


Fig. 11 LVPECL Output Drive HCSL Termination

### LVPECL Output V<sub>swing</sub> Adjustment

It is suggested to add another cross 100ohm at TX side to tune the LVPECL output V<sub>swing</sub> without changing the optimal 150ohm pull-down bias in Fig. 12. This form of double termination can reduce the V<sub>swing</sub> in 1/2 of the original at the RX side. By fine tuning the 100ohm resistor at the TX side with larger values like 150 to 200ohm, one can increase the V<sub>swing</sub> by > 1/2 ratio.

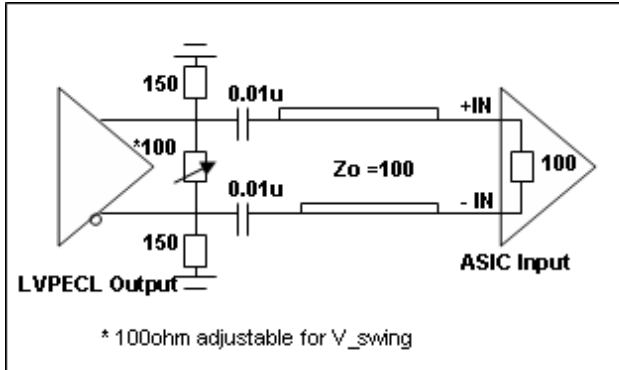
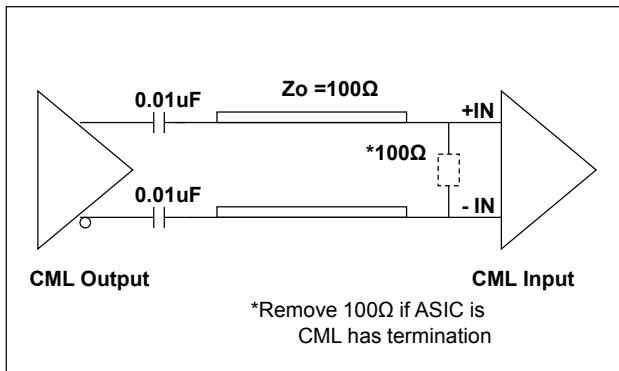


Fig. 12 LVPECL Output V<sub>swing</sub> Adjustment

### CML AC Output Drive

CML is implemented mostly via AC coupling. With AC coupling, CML can drive LVPECL and LVDS inputs as well with an external 100 ohm equivalent differential termination.



### Clock Jitter Definitions

#### Total jitter= RJ + DJ

Random Jitter (RJ) is unpredictable and unbounded timing noise that can fit in a Gaussian math distribution in RMS. RJ test values are directly related with how long or how many test samples are available. Deterministic Jitter (DJ) is timing jitter that is predictable and periodic in fixed interference frequency. Total Jitter (TJ) is the combination of random jitter and deterministic jitter: , where is a factor based on total test sample count. JEDEC std. specifies digital clock TJ in 10k random samples.

### Phase Jitter

Phase noise is short-term random noise attached on the clock carrier and it is a function of the clock offset from the carrier, for example dBc/Hz@10kHz which is phase noise power in 1-Hz normalized bandwidth vs. the carrier power @10kHz offset. Integration of phase noise in plot over a given frequency band yields RMS phase jitter, for example, to specify phase jitter <=1ps at 12k to 20MHz offset band as SONET standard specification.

### PCIe Ref\_CLK Jitter

PCIe reference clock jitter specification requires testing via the PCI-SIG jitter tool, which is regulated by US PCI-SIG organization. The jitter tool has PCIe Serdes embedded filter to calculate the equivalent jitter that relates to data link eye closure. Direct peak-peak jitter or phase jitter test data, normally is higher than jitter measure using PCI-SIG jitter tool. It has high-frequency jitter and low-frequency jitter spec. limit. For more information, please refer to the PCI-SIG website: <http://www.pcisig.com/specifications/pcieexpress/>

### Device Thermal Calculation

Fig. 13 shows the JEDEC thermal model in a 4-layer PCB.

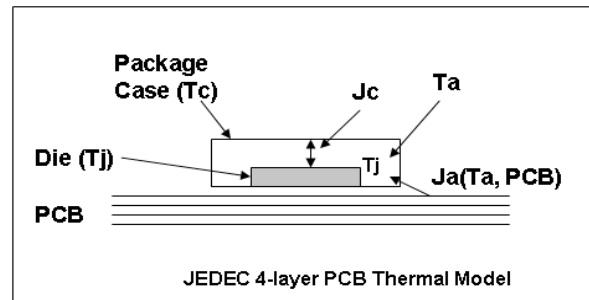


Fig. 13 JEDEC IC Thermal Model

Important factors to influence device operating temperature are:

- 1) The power dissipation from the chip (P<sub>chip</sub>) is after subtracting power dissipation from external loads. Generally it can be the no-load device I<sub>dd</sub>
- 2) Package type and PCB stack-up structure, for example, 1oz 4 layer board. PCB with more layers and are thicker has better heat dissipation

3) Chassis air flow and cooling mechanism. More air flow M/s and adding heat sink on device can reduce device final die junction temperature Tj

The individual device thermal calculation formula:

$$T_j = T_a + P_{chip} \times J_a$$

$$T_c = T_j - P_{chip} \times J_c$$

J<sub>a</sub> \_\_\_\_ Package thermal resistance from die to the ambient air in C/W unit; This data is provided in JEDEC model simulation. An air flow of 1m/s will reduce J<sub>a</sub> (still air) by 20~30%

J<sub>c</sub> \_\_\_\_ Package thermal resistance from die to the package case in C/W unit

T<sub>j</sub> \_\_\_\_ Die junction temperature in C (industry limit <125C max.)

T<sub>a</sub> \_\_\_\_ Ambient air temperature in C

T<sub>c</sub> \_\_\_\_ Package case temperature in C

P<sub>chip</sub> \_\_\_\_ IC actually consumes power through I<sub>ee</sub>/GND current

#### Thermal calculation example

To calculate T<sub>j</sub> and T<sub>c</sub> of PI6CV304 in an SOIC-8 package:

Step 1: Go to Pericom web to find J<sub>a</sub>=157 C/W, J<sub>c</sub>=42 C/W

<http://www.pericom.com/support/packaging/packaging-mechanicals-and-thermal-characteristics/>

Step 2: Go to device datasheet to find I<sub>dd</sub>=40mA max.

I <sub>DD</sub>	Supply Current	C <sub>L</sub> = 33pF/33MHz	20	mA
		C <sub>L</sub> = 33pF/60MHz	40	
		C <sub>L</sub> = 22pF/80MHz	35	
		C <sub>L</sub> = 15pF/100MHz	32	
		C <sub>L</sub> = 10pF/125MHz	28	
		C <sub>L</sub> = 10pF/155MHz	41	

Step 3: P<sub>total</sub> = 3.3V x 40mA = 0.132W

Step 4: If T<sub>a</sub>=85C

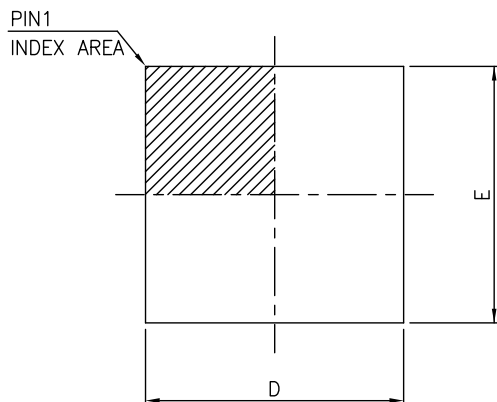
$$T_j = 85 + J_a \times P_{total} = 85 + 25.9 = 105.7C$$

$$T_c = T_j + J_c \times P_{total} = 105.7 - 5.54 = 100.1C$$

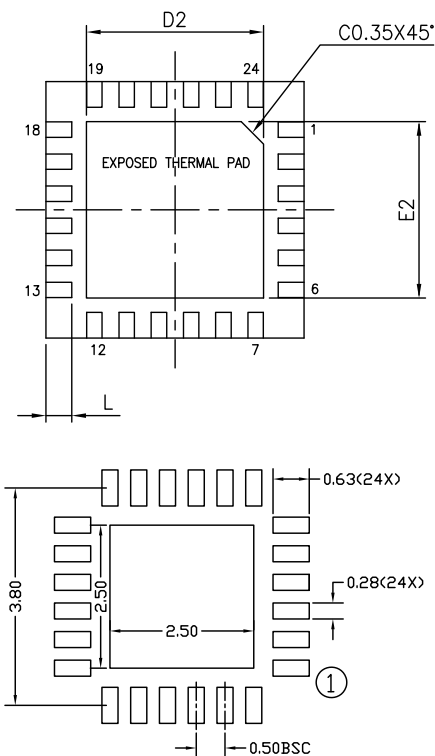
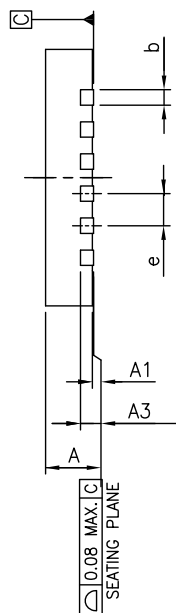
Note:

The above calculation is directly using I<sub>dd</sub> current without subtracting the load power, so it is a conservative estimation. For more precise thermal calculation, use P<sub>unload</sub> or P<sub>chip</sub> from device I<sub>ee</sub> or GND current to calculate T<sub>j</sub>, especially for LVPECL buffer ICs that have a 150ohm pull-down and equivalent 100ohm differential RX load.

### Packaging Mechanical: 24-pin TQFN (ZD)



SYMBOLS	MIN.	NOM.	MAX.
A	—	—	1.00
A1	0.00	0.02	0.05
A3	0.20 REF.		
b	0.18	0.25	0.30
D	3.90	4.00	4.10
E	3.90	4.00	4.10
e	0.50 BSC		
D2	2.15	—	2.80
E2	2.15	—	2.80
L	0.30	0.40	0.50



RECOMMENDED LAND PATTERN (TOP VIEW)

PKG : ZD24

#### NOTES :

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220.



DATE: 01/24/13

DESCRIPTION: 24-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZD24

DOCUMENT CONTROL #: PD-2100

REVISION: A

### Ordering Information(1,2,3)

Ordering Code	Package Code	Package Description
PI6C59S6005ZDIE	ZD	Pb-free & Green, 24-pin TQFN

#### Notes:

1. Thermal characteristics can be found on the company web site at [www.pericom.com/packaging/](http://www.pericom.com/packaging/)
2. E = Pb-free & Green
3. X suffix = Tape/Reel